

**Silicon N-P-N
Power Transistors**

General-Purpose Types for
Medium-Power Applications

Features:

- High-temperature characterization
- High dc beta at 200 mA
- Full switching-time characterization at 200 mA

These devices are available with either 1½-inch leads (TO-5 package) or ½-inch leads (TO-39 package). The longer-lead versions are specified by suffix "L" after the type number; the shorter-lead versions are specified by suffix "S" after the type number.

RCA-2N1479-2N1482 are diffused-junction silicon n-p-n power transistors. These transistors are intended for a wide variety of applications in industrial and military equipment. They are particularly useful in power-switching circuits such as in dc-to-dc converters, inverters, choppers, solenoid and relay controls; in oscillator, regulator, and pulse-amplifier

circuits; and as class A and class B push-pull audio and servo amplifiers.

These transistors feature high beta at high current, and excellent high-temperature performance. They employ the JEDEC TO-39 or TO-5 hermetic package.

Maximum Ratings, Absolute-Maximum Values:

- *COLLECTOR-TO-BASE VOLTAGE
- *COLLECTOR-TO-EMITTER VOLTAGE:
With base open, sustaining
- With emitter-to-base reverse biased
($V_{EB} = 1.5$ volts)
- *EMITTER-TO-BASE VOLTAGE
- *COLLECTOR CURRENT
- *EMITTER CURRENT
- *BASE CURRENT
- *TRANSISTOR DISSIPATION:
(See Rating Chart Fig. 1):
At case temperature of 25° C
- At case temperature of 100° C
- TEMPERATURE RANGE:
Operating and Storage

	2N1479	2N1480	
	2N1481	2N1482	
V_{CBO}	60	100	V
$V_{CEO(sus)}$	40	55	V
V_{CEX}	60	100	V
V_{EB}	12	12	V
I_C	1.5	1.5	A
I_E	-1.75	-1.75	A
I_B		1	A
P_T			
	5	5	W
	2.86	2.86	W
	-65 to +200		°C

2N1479-80-81-82 Silicon N-P-N Transistors

*In accordance with JEDEC registration data

ELECTRICAL CHARACTERISTICS, At Case Temperature (T_C) = 25°C unless otherwise specified

CHARACTERISTIC	SYMBOL	TEST CONDITIONS						LIMITS								UNITS
		VOLTAGE V dc			CURRENT mA dc			2N1479		2N1480		2N1481		2N1482		
		V _{CB}	V _{CE}	V _{EB}	I _C	I _B	I _E	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Collector Cutoff Current: $T_C = 150^\circ\text{C}$	I _{CBO}	30					0	10	10	10	10	10	10	10	μA	
		30					0	500	500	500	500	500	500	500		
Emitter Cutoff Current	I _{EBO}			12	0			10	10	10	10	10	10	10	μA	
Collector-To-Emitter Voltage: With base-emitter junction reverse-biased	V _{CEX}			1.5	0.25			60	100	60	100	60	100	100	V	
With base open, sustaining	V _{CEO(sus)}				50	0		40	55	40	55	40	55	55		
Base-To-Emitter Voltage	V _{BE}		4		200			3	3	3	3	3	3	3	V	
DC Current Transfer Ratio	h _{FE}		4		200		20	60	20	60	35	100	35	100		
Small-Signal Current Transfer Ratio	h _{fe}		4		5		50 Typ.	50 Typ.	50 Typ.	50 Typ.	50 Typ.	50 Typ.	50 Typ.	50 Typ.		
DC Collector-To-Emitter Saturation Resistance	R _s				200 200	20 10		7	7	7	7	7	7	7	Ω	
Collector-To-Base Capacitance	C _{ob}	40						150 Typ.	150 Typ.	150 Typ.	150 Typ.	150 Typ.	150 Typ.	150 Typ.	pF	
Thermal Time Constant	τ ₁							10 Typ.	10 Typ.	10 Typ.	10 Typ.	10 Typ.	10 Typ.	10 Typ.	ms	
Alpha-Cutoff Frequency	f _{αB}	28			5			1.5 Typ.	1.5 Typ.	1.5 Typ.	1.5 Typ.	1.5 Typ.	1.5 Typ.	1.5 Typ.	MHz	
Switching Time:																
Delay Time	t _d ^o							0.2 Typ.	0.2 Typ.	0.2 Typ.	0.2 Typ.	0.2 Typ.	0.2 Typ.	0.2 Typ.	μs	
Rise Time	t _r ^o							1 Typ.	1 Typ.	1 Typ.	1 Typ.	1 Typ.	1 Typ.	1 Typ.		
Storage Time	t _s ^o							0.6 Typ.	0.6 Typ.	0.6 Typ.	0.6 Typ.	0.6 Typ.	0.6 Typ.	0.6 Typ.		
Fall Time	t _f ^o							1 Typ.	1 Typ.	1 Typ.	1 Typ.	1 Typ.	1 Typ.	1 Typ.		
Thermal Resistance:															°C/W	
Junction-to-case	R _{θJC}							35	35	35	35	35	35	35		
Junction-to-free air	R _{θJFA}							200	200	200	200	200	200	200		

*In accordance with JEDEC registration data
 *I_C = 200 mA, I_{B1} = 20 mA, I_{B2} = -8.5 mA; see Figs. 6 and 7.

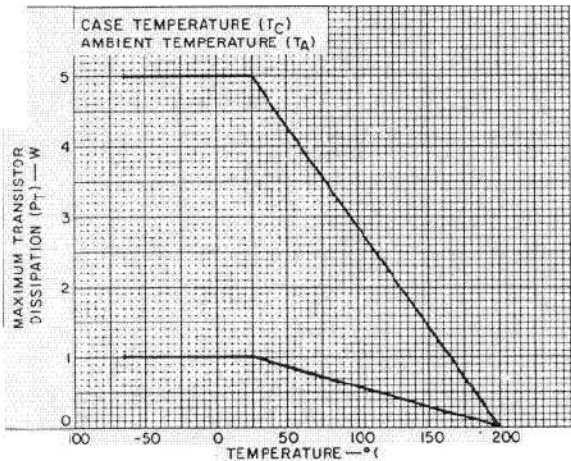


Fig. 1 - Derating chart for all types.

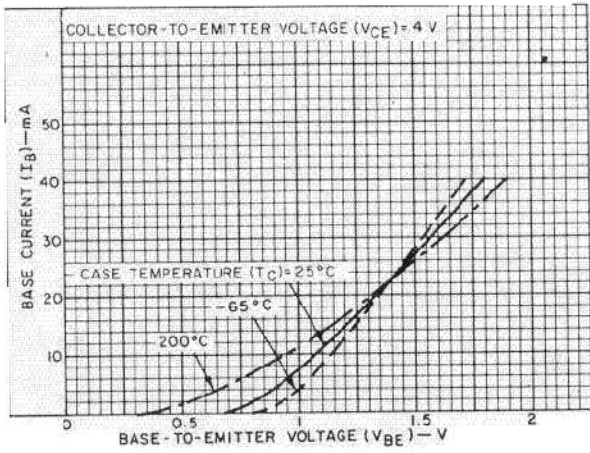


Fig.2 - Typical input characteristics for all types.

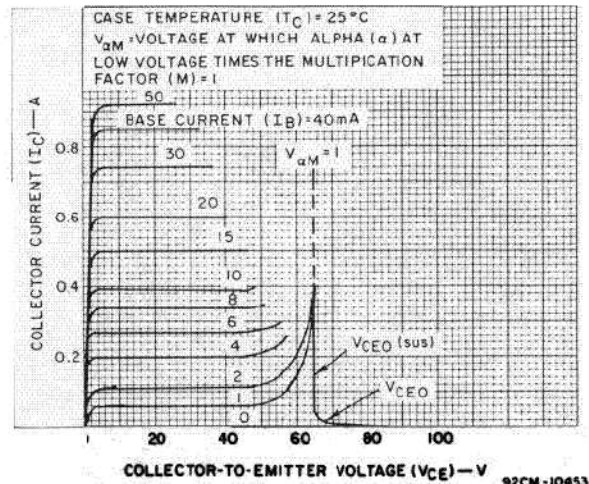


Fig.3 - Typical output characteristics for all types.

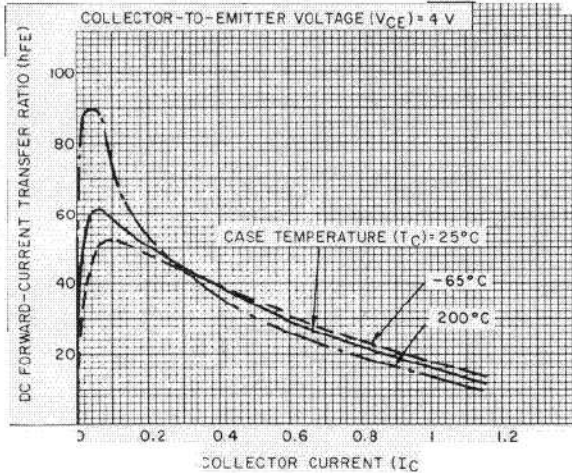


Fig.4 - Typical dc beta characteristics for all types.

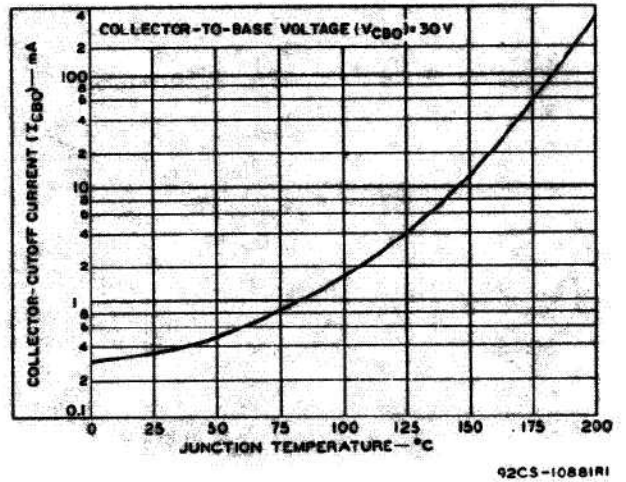


Fig.5 - Typical leakage characteristics for all types.

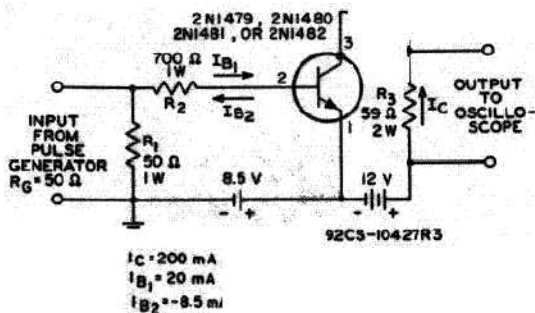


Fig.6 - Test circuit for measurement of saturated switching times.

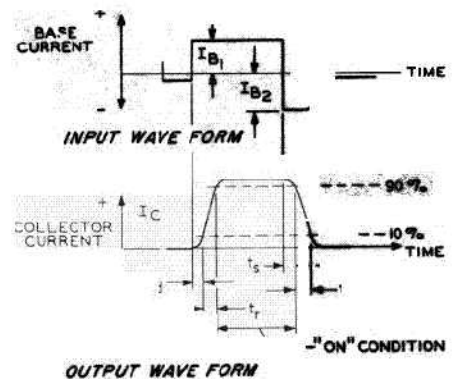
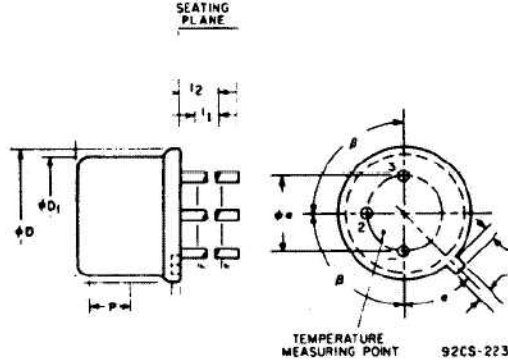


Fig.7 - Oscilloscope display for measurement of switching times (test circuit in Fig. 6).

DIMENSIONAL OUTLINE FOR ALL TYPES



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
ϕa	0.190	0.210	4.83	5.33	
A	0.240	0.260	6.10	6.60	
ϕb	0.016	0.021	0.406	0.533	2
ϕb_2	0.016	0.019	0.406	0.483	2
ϕD	0.350	0.370	8.89	9.40	
ϕD_1	0.305	0.335	8.00	8.51	
h	0.009	0.041	0.229	1.04	
j	0.028	0.034	0.711	0.864	
k	0.029	0.040	0.737	1.02	3
L long lead	1.500		38.10		2
L short lead	0.500		12.70		2
l_1		0.050		1.27	2
l_2	0.250		6.35		2
P	0.100		2.54		1
Q					4
α	45° NOMINAL				
β	90° NOMINAL				

- Note 1: This zone is controlled for automatic handling. The variation in actual diameter within this zone shall not exceed 0.010 in. (0.254 mm).
- Note 2: (Three leads) ϕb_2 applies between l_1 and l_2 . ϕb applies between l_2 and l . Diameter is uncontrolled in l_1 .
- Note 3: Measured from maximum diameter of the actual device.
- Note 4: Details of outline in this zone optional.

TERMINAL CONNECTIONS

- Lead 1 - Emitter
- Lead 2 - Base
- Casc, Lead 3 - Collector

When incorporating RCA Solid State Devices in equipment, it is recommended that the designer refer to "Operating Considerations for RCA Solid State Devices", Form No. 1CE-402, available on request from RCA Solid State Division, Box 3200, Somerville, N.J. 08876.